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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	16MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	17
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 12x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf720-i-ss

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TABLE 3-1: STATUS BITS AND THEIR SIGNIFICANCE

$\overline{POR}$	$\overline{BOR}$	$\overline{TO}$	$\overline{PD}$	Condition
0	x	1	1	Power-on Reset or LDO Reset
0	x	0	x	Illegal, $\overline{TO}$ is set on $\overline{POR}$
0	x	x	0	Illegal, $\overline{PD}$ is set on $\overline{POR}$
1	0	1	1	Brown-out Reset
1	1	0	1	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	$\overline{MCLR}$ Reset during normal operation
1	1	1	0	$\overline{MCLR}$ Reset during Sleep or interrupt wake-up from Sleep

TABLE 3-2: RESET CONDITION FOR SPECIAL REGISTERS(2)

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	0000h	0001 1xxx	---- --0x
$\overline{MCLR}$ Reset during normal operation	0000h	000u uuuu	---- --uu
$\overline{MCLR}$ Reset during Sleep	0000h	0001 0uuu	---- --uu
WDT Reset	0000h	0000 1uuu	---- --uu
WDT Wake-up	PC + 1	uuu0 0uuu	---- --uu
Brown-out Reset	0000h	0001 1uuu	---- --u0
Interrupt Wake-up from Sleep	PC + 1(1)	uuu1 0uuu	---- --uu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0'.

Note 1: When the wake-up is due to an interrupt and Global Interrupt Enable bit (GIE) is set, the return address is pushed on the stack and PC is loaded with the interrupt vector (0004h) after execution of PC + 1.

2: If a Status bit is not implemented, that bit will be read as '0'.

3.1 MCLR

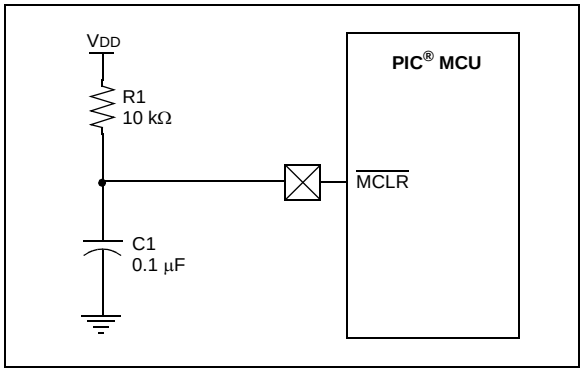
The PIC16(L)F720/721 has a noise filter in the MCLR Reset path. The filter will detect and ignore small pulses.

It should be noted that a Reset does not drive the MCLR pin low.

Voltages applied to the pin that exceed its specification can result in both MCLR Resets and excessive current beyond the device specification during the ESD event. For this reason, Microchip recommends that the MCLR pin no longer be tied directly to VDD. The use of an RC network, as shown in Figure 3-2, is suggested.

An internal MCLR option is enabled by clearing the MCLRE bit in the Configuration Word register. When MCLRE = 0, the Reset signal to the chip is generated internally. When the MCLRE = 1, the RA3/MCLR pin becomes an external Reset input. In this mode, the RA3/MCLR pin has a weak pull-up to VDD. In-Circuit Serial Programming™ is not affected by selecting the internal MCLR option.

FIGURE 3-2: RECOMMENDED MCLR CIRCUIT



3.2 Power-on Reset (POR)

The on-chip POR circuit holds the chip in Reset until VDD has reached a high enough level for proper operation. A maximum rise time for VDD is required. See **Section 23.0 "Electrical Specifications"** for details. If the BOR is enabled, the maximum rise time specification does not apply. The BOR circuitry will keep the device in Reset until VDD reaches VBOR (see **Section 3.5 "Brown-out Reset (BOR)"**).

When the device starts normal operation (exits the Reset condition), device operating parameters (i.e., voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met.

For additional information, refer to Application Note *AN607, Power-up Trouble Shooting* (DS00000607).

3.3 Power-up Timer (PWRT)

The Power-up Timer provides a fixed 72 ms (nominal) time out on power-up only, from POR or Brown-out Reset. The Power-up Timer operates from the WDT oscillator. For more information, see **Section 7.3 "Internal Clock Modes"**. The chip is kept in Reset as long as PWRT is active. The PWRT delay allows the VDD to rise to an acceptable level. A Configuration bit, PWRTE, can disable (if set) or enable (if cleared or programmed) the Power-up Timer. The Power-up Timer should be enabled when Brown-out Reset is enabled, although it is not required.

The Power-up Timer delay will vary from chip-to-chip and vary due to:

- VDD variation
- Temperature variation
- Process variation

See DC parameters for details (**Section 23.0 "Electrical Specifications"**).

Note:	The Power-up Timer is enabled by the PWRTE bit in the Configuration Word.

3.4 Watchdog Timer (WDT)

The WDT has the following features:

- Shares an 8-bit prescaler with Timer0
- Time-out period is from 17 ms to 2.2 seconds, nominal
- Enabled by a Configuration bit

WDT is cleared under certain conditions described in Table 3-3.

3.4.1 WDT OSCILLATOR

The WDT derives its time base from 31 kHz internal oscillator.

4.5.1 INTCON REGISTER

The INTCON register is a readable and writable register, which contains the various enable and flag bits for TMR0 register overflow, PORTB change and external RA2/INT pin interrupts.

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Interrupt Enable bit, GIE of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 4-1: INTCON: INTERRUPT CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE	PEIE	TMR0IE	INTE	RABIE(1)	TMR0IF(2)	INTF	RABIF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **GIE:** Global Interrupt Enable bit
1 = Enables all unmasked interrupts
0 = Disables all interrupts

bit 6 **PEIE:** Peripheral Interrupt Enable bit
1 = Enables all unmasked peripheral interrupts
0 = Disables all peripheral interrupts

bit 5 **TMR0IE:** Timer0 Overflow Interrupt Enable bit
1 = Enables the Timer0 interrupt
0 = Disables the Timer0 interrupt

bit 4 **INTE:** INT External Interrupt Enable bit
1 = Enables the INT external interrupt
0 = Disables the INT external interrupt

bit 3 **RABIE:** PORTA or PORTB Change Interrupt Enable bit(1)
1 = Enables the PORTA or PORTB change interrupt
0 = Disables the PORTA or PORTB change interrupt

bit 2 **TMR0IF:** Timer0 Overflow Interrupt Flag bit(2)
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow

bit 1 **INTF:** INT External Interrupt Flag bit
1 = The INT external interrupt occurred (must be cleared in software)
0 = The INT external interrupt did not occur

bit 0 **RABIF:** PORTA or PORTB Change Interrupt Flag bit
1 = When at least one of the PORTA or PORTB general purpose I/O pins changed state (must be cleared in software)
0 = None of the PORTA or PORTB general purpose I/O pins have changed state

Note 1: The appropriate bits in the IOCB register must also be set.
2: TMR0IF bit is set when Timer0 rolls over. Timer0 is unchanged on Reset and should be initialized before clearing TMR0IF bit.

9.1 ADC Configuration

When configuring and using the ADC, the following functions must be considered:

- Port Configuration
- Channel selection
- ADC conversion clock source
- Interrupt control

9.1.1 PORT CONFIGURATION

When converting analog signals, the I/O pin selected as the input channel should be configured for analog by setting the associated TRIS and ANSEL bits. Refer to **Section 6.0 "I/O Ports"** for more information.

Note:	Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

9.1.2 CHANNEL SELECTION

There are 14 channel selections available:

- AN<11:0> pins
- Temperature Indicator
- FVR (Fixed Voltage Reference) Output

Refer to **Section 11.0 "Temperature Indicator Module"** and **Section 10.0 "Fixed Voltage Reference"** for more information on these channel selections.

The CHS bits of the ADCON0 register determine which channel is connected to the sample and hold circuit.

When changing channels, a delay is required before starting the next conversion. Refer to **Section 9.2 "ADC Operation"** for more information.

9.1.3 CONVERSION CLOCK

The source of the conversion clock is software-selectable via the ADCS bits of the ADCON1 register. There are seven possible clock options:

- FOSC/2
- FOSC/4
- FOSC/8
- FOSC/16
- FOSC/32
- FOSC/64
- FRC (dedicated internal oscillator)

The time to complete one bit conversion is defined as TAD. One full 8-bit conversion requires 10 TAD periods as shown in Figure 9-2.

For correct conversion, the appropriate TAD specification must be met. Refer to the A/D conversion requirements in **Section 23.0 "Electrical Specifications"** for more information. Table 9-1 gives examples of appropriate ADC clock selections.

Note:	Unless using the FRC, any changes in the system clock frequency will change the ADC clock frequency, which may adversely affect the ADC result.

TABLE 9-1: ADC CLOCK PERIOD (TAD) VS. DEVICE OPERATING FREQUENCIES

ADC Clock Period (TAD)		Device Frequency (FOSC)			
ADC Clock Source	**ADCS<2:0>**	**16 MHz**	**8 MHz**	**4 MHz**	**1 MHz**
FOSC/2	000	125 ns(2)	250 ns(2)	500 ns(2)	2.0 μs
FOSC/4	100	250 ns(2)	500 ns(2)	1.0 μs	4.0 μs
FOSC/8	001	0.5 μs(2)	1.0 μs	2.0 μs	8 μs(5)
FOSC/16	101	1.0 μs	2.0 μs	4.0 μs	16.0 μs(5)
FOSC/32	010	2.0 μs	4.0 μs	8 μs(5)	32.0 μs(3)
FOSC/64	110	4.0 μs	8 μs(5)	16.0 μs(5)	64.0 μs(3)
FRC	x11	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)

Legend: Shaded cells are outside of the recommended range.

Note 1: The FRC source has a typical TAD time of 1.6 μs for VDD.

2: These values violate the minimum required TAD time.

3: For faster conversion times, the selection of another clock source is recommended.

4: When the device frequency is greater than 1 MHz, the FRC clock source is only recommended if the conversion will be performed during Sleep.

5: Recommended values for VDD ≤ 2.0V and temperature -40°C to 85°C. The 16.0 μs setting should be avoided for temperature > 85°C.

13.3 Timer1 Prescaler

Timer1 has four prescaler options allowing 1, 2, 4 or 8 divisions of the clock input. The T1CKPS bits of the T1CON register control the prescaler counter. The prescale counter is not directly readable or writable; however, the prescaler counter is cleared upon a write to TMR1H or TMR1L.

13.4 Timer1 Operation in Asynchronous Counter Mode

If the control bit $\overline{\text{T1SYNC}}$ of the T1CON register is set, the external clock input is not synchronized. The timer increments asynchronously to the internal phase clocks. If external clock source is selected then the timer will continue to run during Sleep and can generate an interrupt on overflow, which will wake-up the processor. However, special precautions in software are needed to read/write the timer (see **Section 13.4.1 "Reading and Writing Timer1 in Asynchronous Counter Mode"**).

Note:	When switching from synchronous to asynchronous operation, it is possible to skip an increment. When switching from asynchronous to synchronous operation, it is possible to produce an additional increment.

13.4.1 READING AND WRITING TIMER1 IN ASYNCHRONOUS COUNTER MODE

Reading TMR1H or TMR1L while the timer is running from an external asynchronous clock will ensure a valid read (taken care of in hardware). However, the user should keep in mind that reading the 16-bit timer in two 8-bit values itself, poses certain problems, since the timer may overflow between the reads.

For writes, it is recommended that the user simply stop the timer and write the desired values. A write contention may occur by writing to the timer registers, while the register is incrementing. This may produce an unpredictable value in the TMR1H:TMR1L register pair.

13.5 Timer1 Gate

Timer1 can be configured to count freely or the count can be enabled and disabled using Timer1 gate circuitry. This is also referred to as Timer1 gate count enable.

Timer1 gate can also be driven by multiple selectable sources.

13.5.1 TIMER1 GATE COUNT ENABLE

The Timer1 gate is enabled by setting the TMR1GE bit of the T1GCON register. The polarity of the Timer1 gate is configured using the T1GPOL bit of the T1GCON register.

When Timer1 Gate ($\overline{\text{T1G}}$) input is active, Timer1 will increment on the rising edge of the Timer1 clock source. When Timer1 gate input is inactive, no incrementing will occur and Timer1 will hold the current count. See Figure 13-3 for timing details.

TABLE 13-3: TIMER1 GATE ENABLE SELECTIONS

T1CLK	T1GPOL	$\overline{\text{T1G}}$	Timer1 Operation
↑	0	0	Counts
↑	0	1	Holds Count
↑	1	0	Holds Count
↑	1	1	Counts

13.5.2 TIMER1 GATE SOURCE SELECTION

The Timer1 gate source can be selected from one of four different sources. Source selection is controlled by the T1GSS bits of the T1GCON register. The polarity for each available source is also selectable. Polarity selection is controlled by the T1GPOL bit of the T1GCON register.

TABLE 13-4: TIMER1 GATE SOURCES

T1GSS	Timer1 Gate Source
00	Timer1 Gate Pin
01	Overflow of Timer0 (TMR0 increments from FFh to 00h)
10	Timer2 match PR2 (TMR2 increments to match PR2)
11	Count Enabled by WDT Overflow (Watchdog Time-out interval expired)

13.10 Timer1 Control Register

The Timer1 Control register (T1CON), shown in Register 13-1, is used to control Timer1 and select the various features of the Timer1 module.

REGISTER 13-1: T1CON: TIMER1 CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	U-0	R/W-0
TMR1CS1	TMR1CS0	T1CKPS1	T1CKPS0	—	$\overline{\text{T1SYNC}}$	—	TMR1ON
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **TMR1CS<1:0>:** Timer1 Clock Source Select bits
- 11 = Reserved
- 10 = Timer1 clock source is pin or oscillator. External clock from T1CKI pin (on the rising edge)
- 01 = Timer1 clock source is system clock (FOSC)
- 00 = Timer1 clock source is instruction clock (FOSC/4)

bit 5-4 **T1CKPS<1:0>:** Timer1 Input Clock Prescale Select bits
- 11 = 1:8 Prescale value
- 10 = 1:4 Prescale value
- 01 = 1:2 Prescale value
- 00 = 1:1 Prescale value

bit 3 **Unimplemented:** Read as '0'

bit 2 **$\overline{\text{T1SYNC}}$:** Timer1 External Clock Input Synchronization Control bit

TMR1CS<1:0> = 1X
- 1 = Do not synchronize external clock input
- 0 = Synchronize external clock input with system clock (FOSC)

TMR1CS<1:0> = 0X

This bit is ignored. Timer1 uses the internal clock when TMR1CS<1:0> = 1X.

bit 1 **Unimplemented:** Read as '0'

bit 0 **TMR1ON:** Timer1 On bit
- 1 = Enables Timer1
- 0 = Stops Timer1

Clears Timer1 gate flip-flop

16.0 ADDRESSABLE UNIVERSAL SYNCHRONOUS ASYNCHRONOUS RECEIVER TRANSMITTER (AUSART)

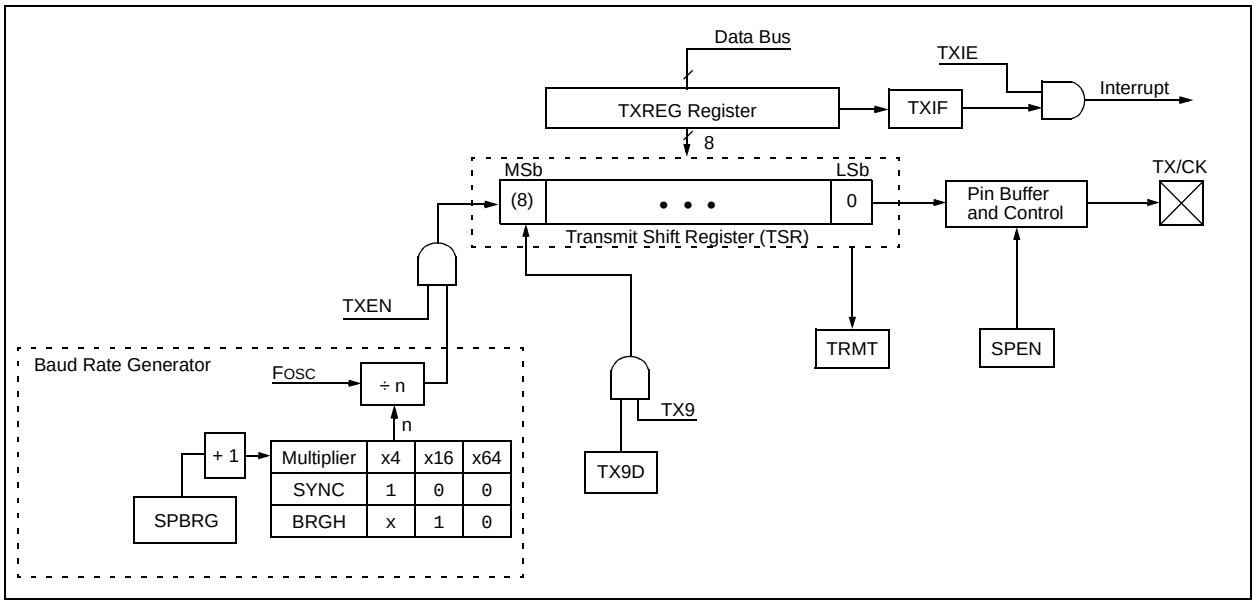
The Addressable Universal Synchronous Asynchronous Receiver Transmitter (AUSART) module is a serial I/O communications peripheral. It contains all the clock generators, shift registers and data buffers necessary to perform an input or output serial data transfer independent of device program execution. The AUSART, also known as a Serial Communications Interface (SCI), can be configured as a full-duplex asynchronous system or half-duplex synchronous system. Full Duplex mode is useful for communications with peripheral systems, such as CRT terminals and personal computers. Half Duplex Synchronous mode is intended for communications with peripheral devices, such as A/D or D/A integrated circuits, serial EEPROMs or other microcontrollers. These devices typically do not have internal clocks for baud rate generation and require the external clock signal provided by a master synchronous device.

The AUSART module includes the following capabilities:

- Full-duplex asynchronous transmit and receive
- Two-character input buffer
- One-character output buffer
- Programmable 8-bit or 9-bit character length
- Address detection in 9-bit mode
- Input buffer overrun error detection
- Received character framing error detection
- Half-duplex synchronous master
- Half-duplex synchronous slave
- Sleep operation

Block diagrams of the AUSART transmitter and receiver are shown in Figure 16-1 and Figure 16-2.

FIGURE 16-1: AUSART TRANSMIT BLOCK DIAGRAM



16.1 AUSART Asynchronous Mode

The AUSART transmits and receives data using the standard non-return-to-zero (NRZ) format. NRZ is implemented with two levels: a VOH Mark state which represents a '1' data bit, and a VOL Space state which represents a '0' data bit. NRZ refers to the fact that consecutively transmitted data bits of the same value stay at the output level of that bit without returning to a neutral level between each bit transmission. An NRZ transmission port idles in the Mark state. Each character transmission consists of one Start bit followed by eight or nine data bits and is always terminated by one or more Stop bits. The Start bit is always a space and the Stop bits are always marks. The most common data format is eight bits. Each transmitted bit persists for a period of 1/(baud rate). An on-chip dedicated 8-bit Baud Rate Generator is used to derive standard baud rate frequencies from the system oscillator. Refer to Table 16-5 for examples of baud rate Configurations.

The AUSART transmits and receives the LSb first. The AUSART's transmitter and receiver are functionally independent, but share the same data format and baud rate. Parity is not supported by the hardware, but can be implemented in software and stored as the ninth data bit.

16.1.1 AUSART ASYNCHRONOUS TRANSMITTER

The AUSART transmitter block diagram is shown in Figure 16-1. The heart of the transmitter is the serial Transmit Shift Register (TSR), which is not directly accessible by software. The TSR obtains its data from the transmit buffer, which is the TXREG register.

16.1.1.1 Enabling the Transmitter

The AUSART transmitter is enabled for asynchronous operations by configuring the following three control bits:

- TXEN = 1
- SYNC = 0
- SPEN = 1

All other AUSART control bits are assumed to be in their default state.

Setting the TXEN bit of the TXSTA register enables the transmitter circuitry of the AUSART. Clearing the SYNC bit of the TXSTA register configures the AUSART for asynchronous operation. Setting the SPEN bit of the RCSTA register enables the AUSART and automatically configures the TX/CK I/O pin as an output.

Note 1: When the SPEN bit is set the RX/DT I/O pin is automatically configured as an input, regardless of the state of the corresponding TRIS bit and whether or not the AUSART receiver is enabled. The RX/DT pin data can be read via a normal PORT read but PORT latch data output is precluded.

2: The TXIF transmitter interrupt flag is set when the TXEN enable bit is set.

16.1.1.2 Transmitting Data

A transmission is initiated by writing a character to the TXREG register. If this is the first character, or the previous character has been completely flushed from the TSR, the data in the TXREG is immediately transferred to the TSR register. If the TSR still contains all or part of a previous character, the new character data is held in the TXREG until the Stop bit of the previous character has been transmitted. The pending character in the TXREG is then transferred to the TSR in one TCY immediately following the Stop bit transmission. The transmission of the Start bit, data bits and Stop bit sequence commences immediately following the transfer of the data to the TSR from the TXREG.

16.1.1.3 Transmit Interrupt Flag

The TXIF interrupt flag bit of the PIR1 register is set whenever the AUSART transmitter is enabled and no character is being held for transmission in TXREG. In other words, the TXIF bit is only clear when TSR is busy with a character and a new character has been queued for transmission in TXREG. The TXIF flag bit is not cleared immediately upon writing TXREG. TXIF becomes valid in the second instruction cycle following the write execution. Polling TXIF immediately following the TXREG write will return invalid results. The TXIF bit is read-only, it cannot be set or cleared by software.

The TXIF interrupt can be enabled by setting the TXIE interrupt enable bit of the PIE1 register. However, the TXIF flag bit will be set whenever TXREG is empty, regardless of the state of the TXIE enable bit.

To use interrupts when transmitting data, set the TXIE bit only when there is more data to send. Clear the TXIE interrupt enable bit upon writing the last character of the transmission to TXREG.

FIGURE 17-4: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 0)

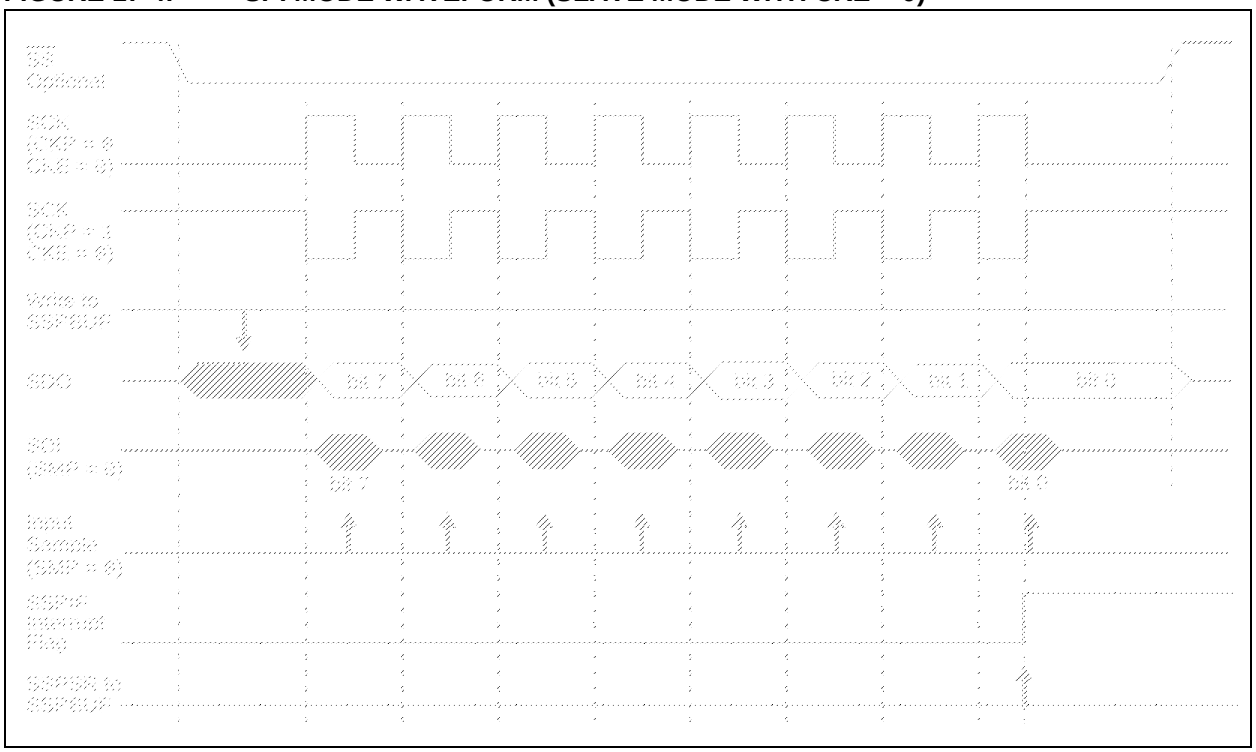
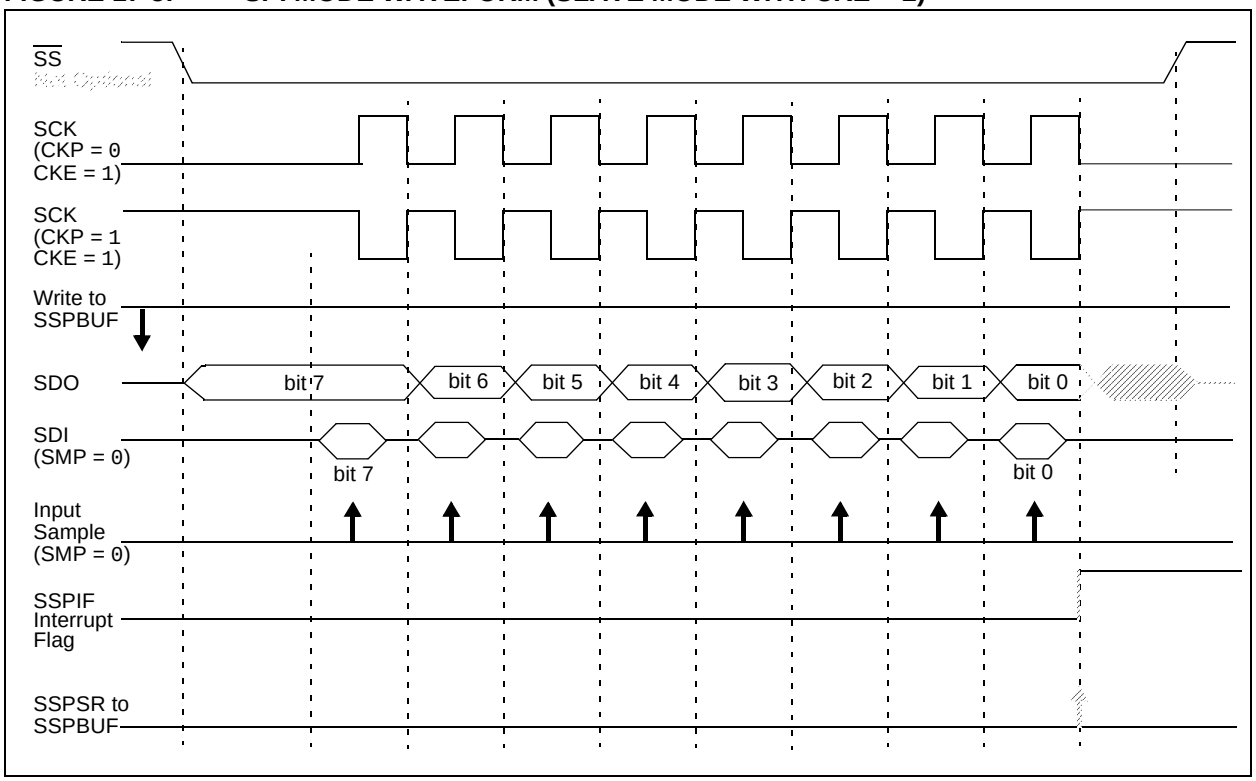


FIGURE 17-5: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 1)



17.2 I²C Mode

The SSP module, in I²C mode, implements all slave functions except general call support. It provides interrupts on Start and Stop bits in hardware to facilitate firmware implementations of the master functions. The SSP module implements the I²C Standard mode specifications:

- I²C Slave mode (7-bit address)
- I²C Slave mode (10-bit address)
- Start and Stop bit interrupts enabled to support firmware Master mode
- Address masking

Two pins are used for data transfer; the SCL pin (clock line) and the SDA pin (data line). The user must configure the two pin's data direction bits as inputs in the appropriate TRIS register. Upon enabling I²C mode, the I²C slew rate limiters in the I/O pads are controlled by the SMP bit of SSPSTAT register. The SSP module functions are enabled by setting the SSPEN bit of SSPCON register.

Data is sampled on the rising edge and shifted out on the falling edge of the clock. This ensures that the SDA signal is valid during the SCL high time. The SCL clock input must have minimum high and low times for proper operation. Refer to **Section 23.0 "Electrical Specifications"**.

FIGURE 17-7: I²C MODE BLOCK DIAGRAM

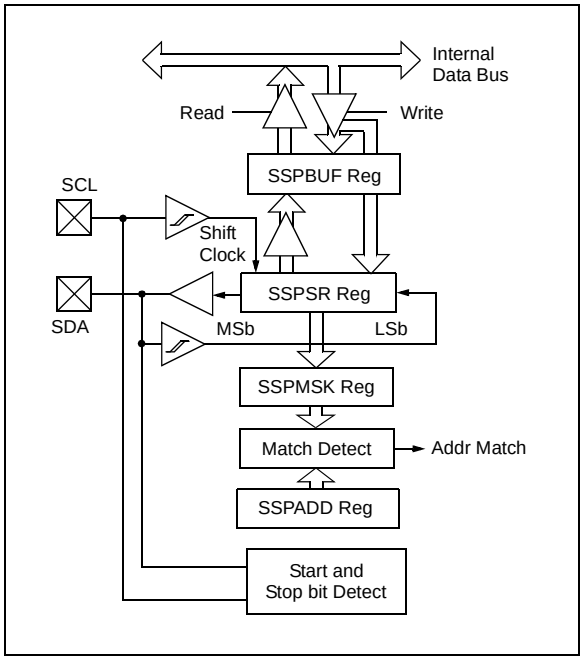
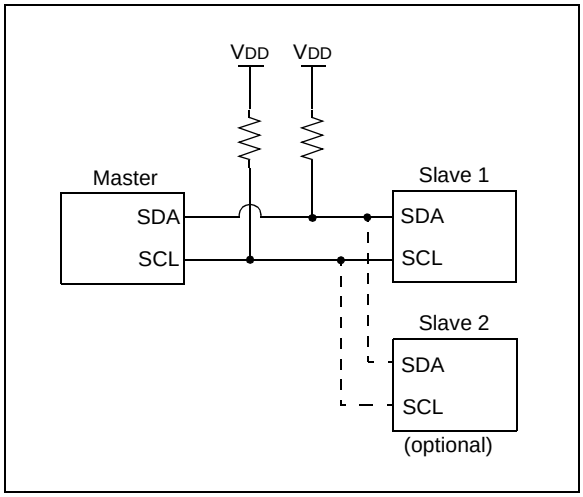


FIGURE 17-8: TYPICAL I²C CONNECTIONS



The SSP module has six registers for I²C operation. They are:

- SSP Control (SSPCON) register
- SSP Status (SSPSTAT) register
- Serial Receive/Transmit Buffer (SSPBUF) register
- SSP Shift Register (SSPSR), not directly accessible
- SSP Address (SSPADD) register
- SSP Address Mask (SSPMSK) register

17.2.1 HARDWARE SETUP

Selection of I²C mode, with the SSPEN bit of the SSPCON register set, forces the SCL and SDA pins to be open drain, provided these pins are programmed as inputs by setting the appropriate TRISC bits. The SSP module will override the input state with the output data, when required, such as for Acknowledge and slave-transmitter sequences.

Note:	Pull-up resistors must be provided externally to the SCL and SDA pins for proper operation of the I²C module.

22.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

22.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

22.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

22.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

23.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS}, PIC16F720/721 ..... -0.3V to +6.5V
Voltage on V_{DD} with respect to V_{SS}, PIC16LF720/721 ..... -0.3V to +4.0V
Voltage on $\overline{MCLR}$ with respect to V_{SS} ..... -0.3V to +9.0V
Voltage on all other pins with respect to V_{SS} ..... -0.3V to (V_{DD} + 0.3V)
Total power dissipation(1) ..... 800 mW
Maximum current out of V_{SS} pin ..... 95 mA
Maximum current into V_{DD} pin ..... 70 mA
Clamp current, I_K (V_{PIN} < 0 or V_{PIN} > V_{DD}) ..... ± 20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by all ports, -40°C ≤ T_A ≤ +85°C for industrial ..... 200 mA
Maximum current sunk by all ports, -40°C ≤ T_A ≤ +125°C for extended ..... 90 mA
Maximum current sourced by all ports, 40°C ≤ T_A ≤ +85°C for industrial ..... 140 mA
Maximum current sourced by all ports, -40°C ≤ T_A ≤ +125°C for extended ..... 65 mA

Note 1: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure above maximum rating conditions for extended periods may affect device reliability.

23.4 DC Characteristics: PIC16(L)F720/721-I/E (Continued)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
D133	TPEW	Erase/Write cycle time	—		2.8	ms	Temperature during programming: 10°C ≤ TA ≤ 40°C
D134*	TRETD	Characteristic Retention	—	40	—	Year	Provided no other specifications are violated
D135	EHEFC	High-Endurance Flash Cell	100K	—	—	E/W	0°C to +60°C Lower byte, Last 128 Addresses in Flash memory

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Negative current is defined as current sourced by the pin.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

TABLE 23-2: OSCILLATOR PARAMETERS(1)

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C								
Param. No.	**Sym**	**Characteristic**	**Freq. Tolerance**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS08	HFOSC	Internal Calibrated HFINTOSC Frequency(2, 3)	± 2%	—	16.0	—	MHz	0°C ≤ TA ≤ +60°C, VDD ≥ 2.5V
			± 3%	—	16.0	—	MHz	+60°C ≤ TA ≤ +85°C, VDD ≥ 2.5V
			± 5%	—	16.0	—	MHz	-40°C ≤ TA ≤ +125°C
OS08	MFOSC	Internal Calibrated MFINTOSC Frequency(2, 3)	± 2%	—	500	—	kHz	0°C ≤ TA ≤ +60°C, VDD ≥ 2.5V
			± 3%	—	500	—	kHz	+60°C ≤ TA ≤ +85°C, VDD ≥ 2.5V
			± 5%	—	500	—	kHz	-40°C ≤ TA ≤ +125°C
OS10*	TIOSC ST	HFINTOSC 16 MHz and MFINTOSC 500 kHz Oscillator Wake-up from Sleep Start-up Time	—	—	5	8	µs	

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at “min” values with an external clock applied to the CLKIN pin. When an external clock input is used, the “max” cycle time limit is “DC” (no clock) for all devices.

2: To ensure these oscillator frequency tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

3: The frequency tolerance of the internal oscillator is ±2% from 0-60°C and ±3% from 60-85°C (see Figure 23-5).

24.0 DC AND AC CHARACTERISTICS GRAPHS AND CHARTS

FIGURE 24-1: PIC16F720/721 MAX IDD vs. FOSC OVER VDD, EC MODE

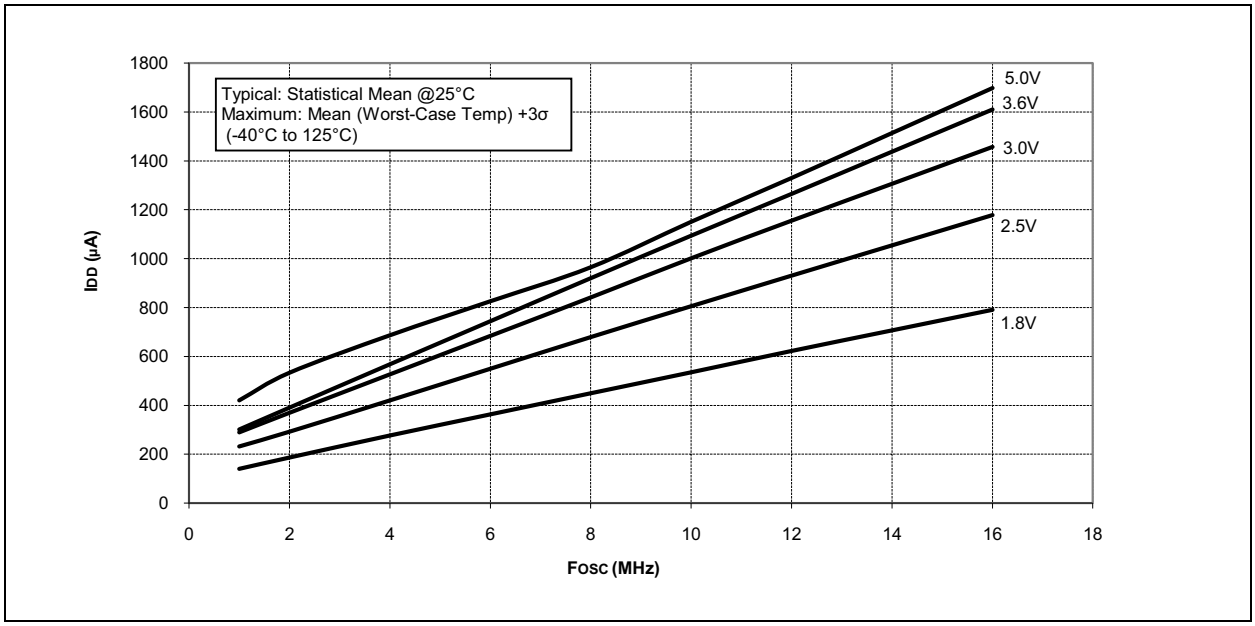


FIGURE 24-2: PIC16F720/721 TYPICAL IDD vs. FOSC OVER VDD, EC MODE

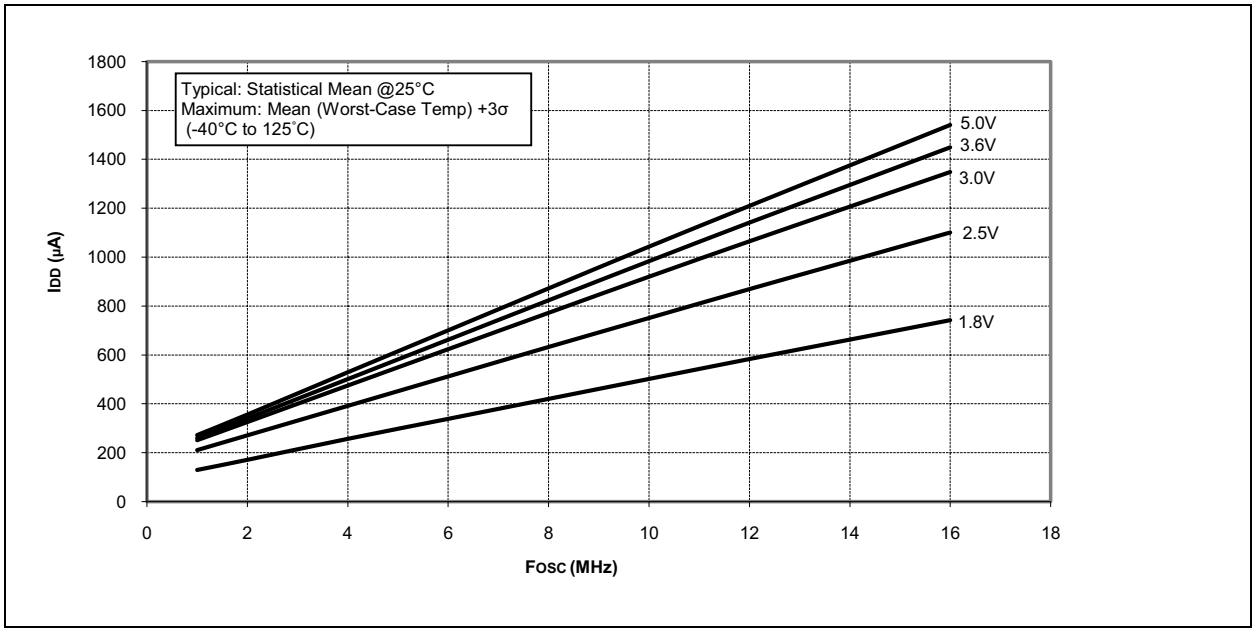


FIGURE 24-3: PIC16LF720/721 MAX. IDD vs. FOSC OVER VDD, EC MODE

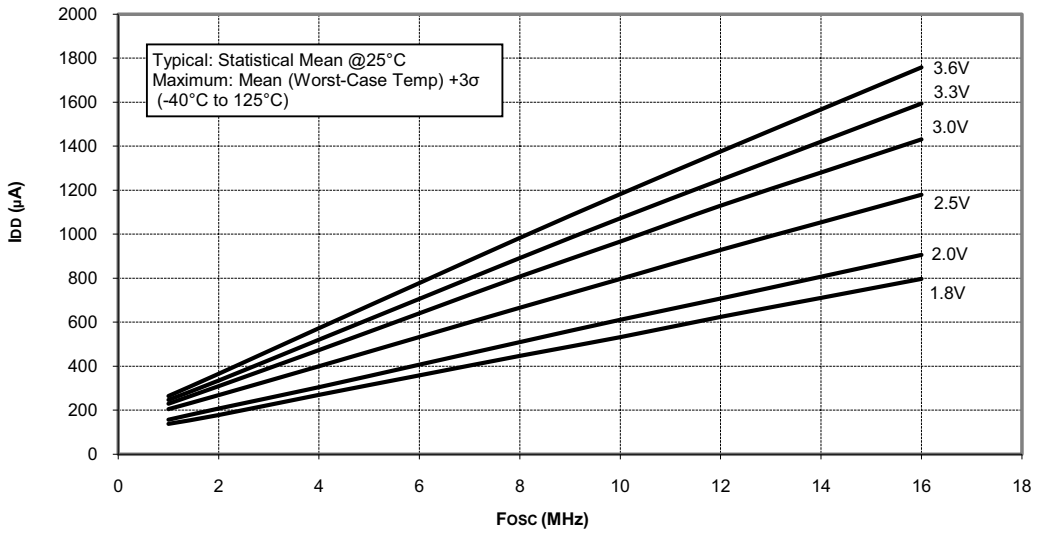


FIGURE 24-4: PIC16LF720/721 TYPICAL IDD vs. FOSC OVER VDD, EC MODE

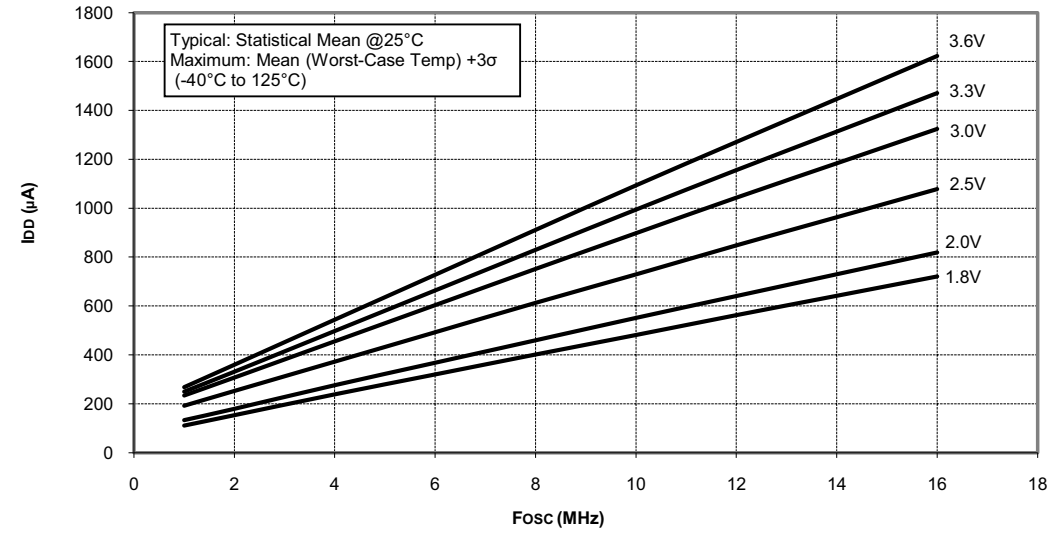


FIGURE 24-5: PIC16F720/721 MAX. IDD vs. FOSC OVER VDD, MFINTOSC

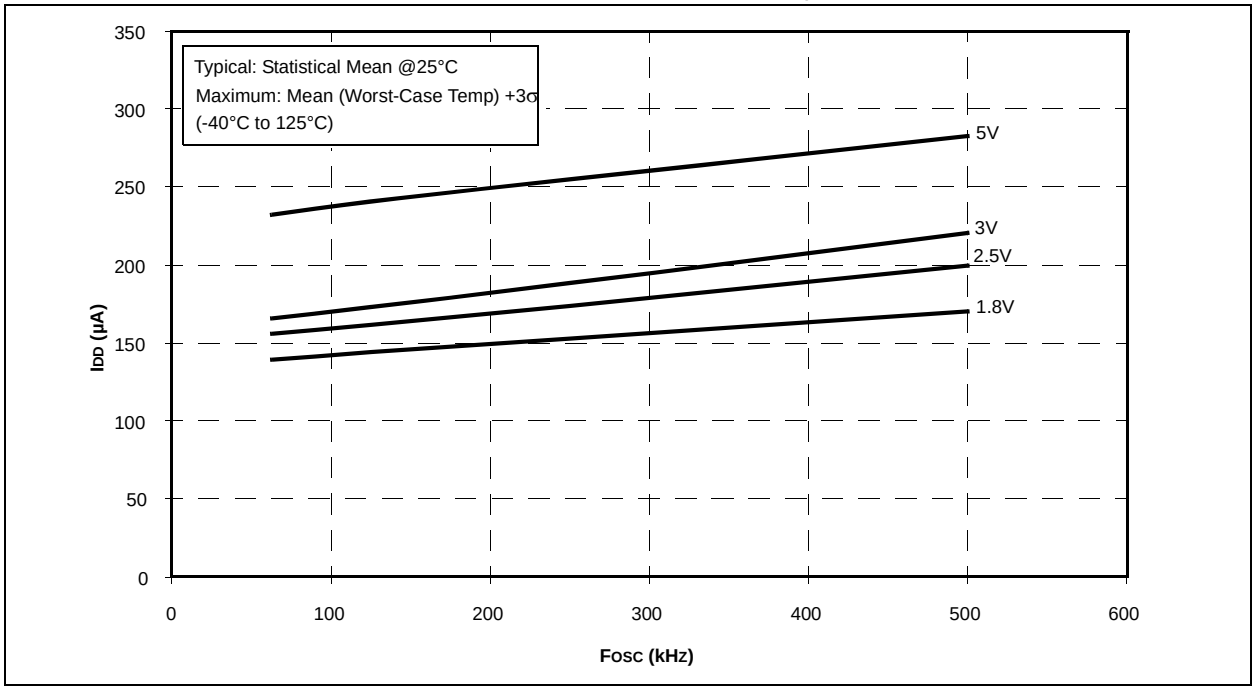
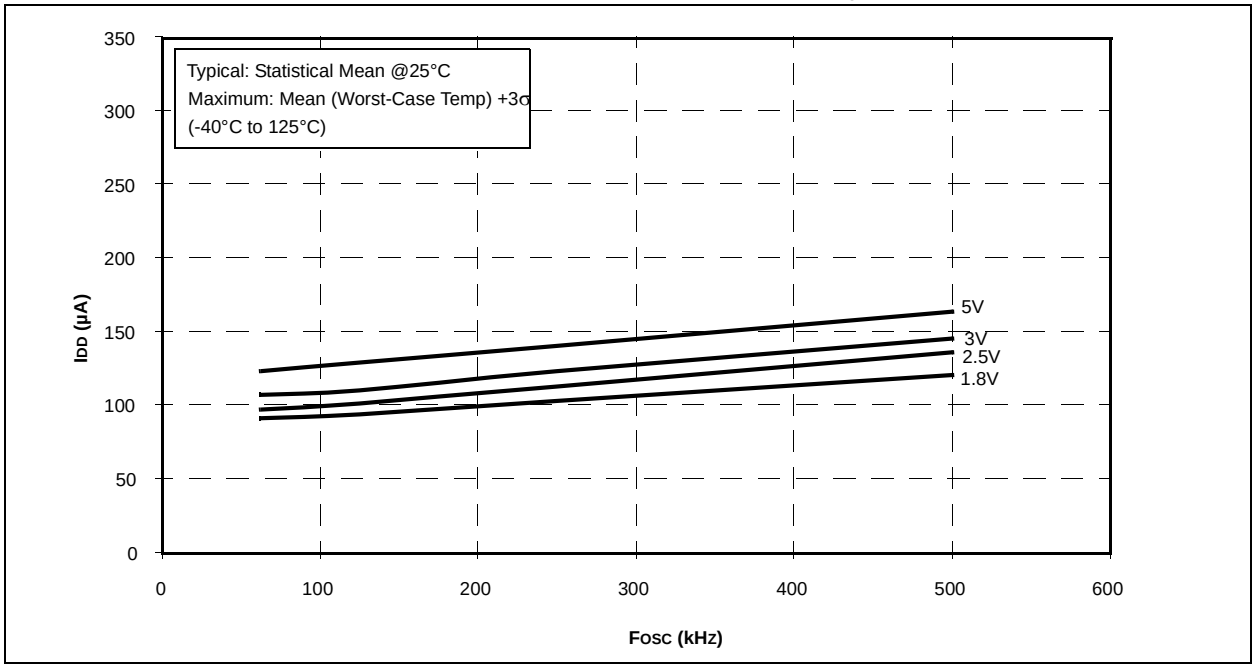


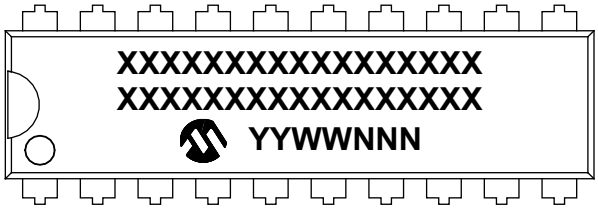
FIGURE 24-6: PIC16F720/721 TYPICAL IDD vs. FOSC OVER VDD, MFINTOSC



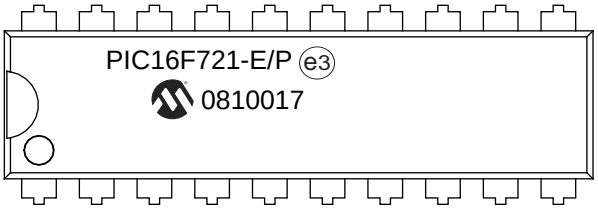
25.0 PACKAGING INFORMATION

25.1 Package Marking Information

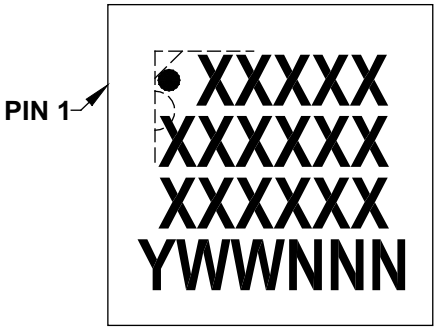
20-Lead PDIP (300 mil)



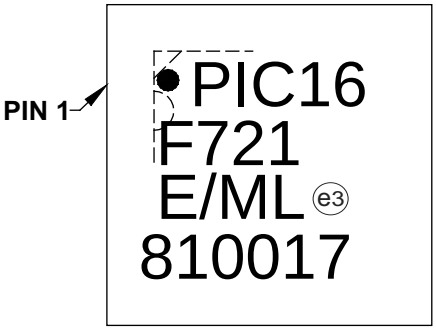
Example



20-Lead QFN (4x4x0.9 mm)



Example



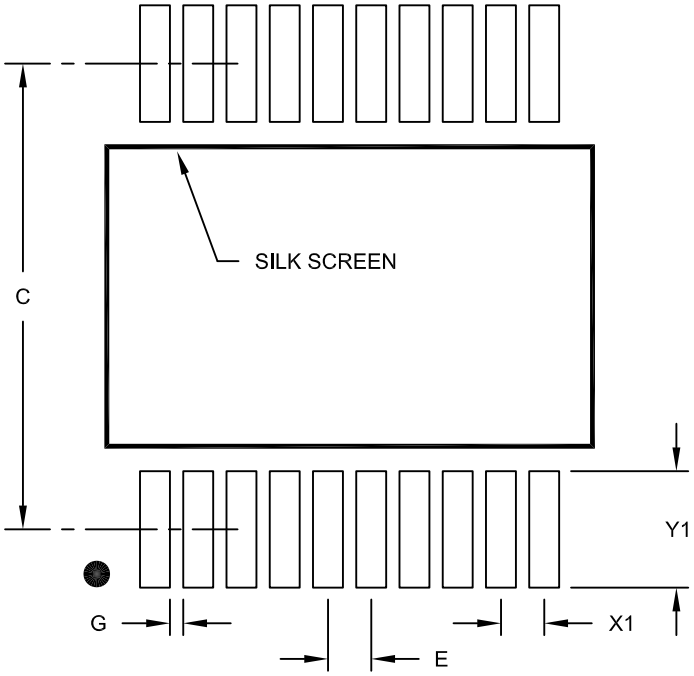
Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC® designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

***** Standard PICmicro® device marking consists of Microchip part number, year code, week code and traceability code. For PICmicro device marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

20-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		7.20	
Contact Pad Width (X20)	X1			0.45
Contact Pad Length (X20)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2072A